

این دیتاشیت توسط توکل الکترونیک تهیه و ارائه شده است.

جهت مشاهده قیمت، موجودی و ثبت سفارش این قطعه به وبسایت توکل الکترونیک مراجعه فرمایید.



مشاهده قیمت و خرید

برای خرید و مشاهده سایر محصولات کلیک کنید



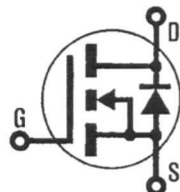
New Jersey Semi-Conductor Products, Inc.

20 STERN AVE.
SPRINGFIELD, NEW JERSEY 07081
U.S.A.

TELEPHONE: (973) 376-2922
(212) 227-6005
FAX: (973) 376-8960

HEXFET® TRANSISTORS

**N-Channel
50 VOLT
POWER MOSFETs**



IRFZ30

IRFZ32

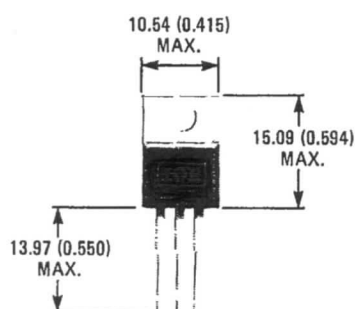
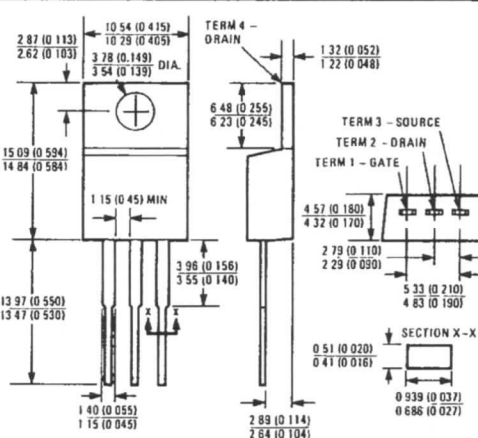
Product Summary

Part Number	V _{DS}	R _{DS(on)}	I _D
IRFZ30	50V	0.05Ω	30A
IRFZ32	50V	0.07Ω	25A

Features:

- Extremely Low R_{DS(on)}
- Compact Plastic Package
- Fast Switching
- Low Drive Current
- Ease of Paralleling
- Excellent Temperature Stability
- Parts Per Million Quality

CASE STYLE AND DIMENSIONS



Case Style TO-220AB
Dimensions in Millimeters and (Inches)



NJ Semi-Conductors reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by NJ Semi-Conductors is believed to be both accurate and reliable at the time of going to press. However, NJ Semi-Conductors assumes no responsibility for any errors or omissions discovered in its use. NJ Semi-Conductors encourages customers to verify that datasheets are current before placing orders.

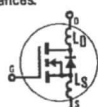
Quality Semi-Conductors

IRFZ30, IRFZ32 Devices

Absolute Maximum Ratings

Parameter	IRFZ30	IRFZ32	Units
V_{DS} Drain - Source Voltage ①	50	50	V
V_{DGR} Drain - Gate Voltage ($R_{GS} = 20\text{ K}\Omega$) ①	50	50	V
$I_D @ T_C = 25^\circ\text{C}$ Continuous Drain Current	30	25	A
$I_D @ T_C = 100^\circ\text{C}$ Continuous Drain Current	19	16	A
I_{DM} Pulsed Drain Current ①	80	60	A
V_{GS} Gate - Source Voltage	± 20		V
$P_D @ T_C = 25^\circ\text{C}$ Max. Power Dissipation	75 (See Fig. 14)		W
Linear Derating Factor	0.6 (See Fig. 14)		W/K ④
I_{LM} Inductive Current, Clamped	80 (See Fig. 15 and 16) $L = 100\mu\text{H}$		A
T_J Operating Junction and Storage Temperature Range	-55 to 150		$^\circ\text{C}$
T_{stg} Lead Temperature	300 (0.063 in. (1.6mm) from case for 10s)		$^\circ\text{C}$

Electrical Characteristics @ $T_C = 25^\circ\text{C}$ (Unless Otherwise Specified)

Parameter	Type	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS} Drain - Source Breakdown Voltage	IRFZ30	60	—	—	V	$V_{GS} = 0\text{V}$
	IRFZ32	50	—	—	V	$I_D = 250\mu\text{A}$
$V_{GS(th)}$ Gate Threshold Voltage	ALL	2.0	—	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
I_{GSS} Gate-Source Leakage Forward	ALL	—	—	500	nA	$V_{GS} = 20\text{V}$
I_{GSS} Gate-Source Leakage Reverse	ALL	—	—	-500	nA	$V_{GS} = -20\text{V}$
I_{DSS} Zero Gate Voltage Drain Current	ALL	—	—	250	μA	$V_{DS} = \text{Max. Rating}, V_{GS} = 0\text{V}$
		—	—	1000	μA	$V_{DS} = \text{Max. Rating} \times 0.8, V_{GS} = 0\text{V}, T_C = 125^\circ\text{C}$
$I_{D(on)}$ On-State Drain Current ②	IRFZ30	30	—	—	A	$V_{DS} > I_{D(on)} \times R_{DS(on)max}, V_{GS} = 10\text{V}$
	IRFZ32	25	—	—	A	
$R_{DS(on)}$ Static Drain-Source On-State Resistance ②	IRFZ30	—	0.045	0.050	Ω	$V_{GS} = 10\text{V}, I_D = 16\text{A}$
	IRFZ32	—	0.065	0.070	Ω	
g_{fs} Forward Transconductance ②	ALL	9.0	12	—	S(U)	$V_{DS} > I_{D(on)} \times R_{DS(on)max}, I_D = 16\text{A}$
C_{iss} Input Capacitance	ALL	—	1250	1600	pF	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1.0\text{ MHz}$ See Fig. 10
C_{oss} Output Capacitance	ALL	—	650	800	pF	
C_{rss} Reverse Transfer Capacitance	ALL	—	130	200	pF	$V_{DD} \approx 25\text{V}, I_D = 16\text{A}, Z_\theta = 50\Omega$ See Fig. 17 (MOSFET switching times are essentially independent of operating temperature.)
$t_{d(on)}$ Turn-On Delay Time	ALL	—	12	25	ns	
t_r Rise Time	ALL	—	18	35	ns	$V_{GS} = 10\text{V}, I_D = 38\text{A}, V_{DS} = 0.8 \text{ Max. Rating.}$ See Fig. 18 for test circuit. (Gate charge is essentially independent of operating temperature.)
$t_{d(off)}$ Turn-Off Delay Time	ALL	—	23	45	ns	
t_f Fall Time	ALL	—	16	35	ns	Measured from the contact screw on tab to center of dia. Measured from the drain lead, 6mm (0.25 in.) from package to center of dia. Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.
Q_g Total Gate Charge (Gate-Source Plus Gate-Drain)	ALL	—	26	30	nC	
Q_{gs} Gate-Source Charge	ALL	—	14	—	nC	Modified MOSFET symbol showing the internal device inductances. 
Q_{gd} Gate-Drain ("Miller") Charge	ALL	—	12	—	nC	
L_D Internal Drain Inductance	ALL	—	3.5	—	nH	Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.
		—	4.5	—	nH	
L_S Internal Source Inductance	ALL	—	7.5	—	nH	

Thermal Resistance

R_{thJC} Junction-to-Case	ALL	—	—	1.67	K/W④	Mounting surface flat, smooth, and greased.
R_{thCS} Case-to-Sink	ALL	—	1.0	—	K/W④	
R_{thJA} Junction-to-Ambient	ALL	—	—	80	K/W④	Typical socket mount

IRFZ30, IRFZ32 Devices

T-39-11

Source-Drain Diode Ratings and Characteristics

I_S	Continuous Source Current (Body Diode)	IRFZ30	—	—	30	A	Modified MOSFET symbol showing the integral reverse P-N junction rectifier.
		IRFZ32	—	—	25	A	
I_{SM}	Pulse Source Current (Body Diode) ③	IRFZ30	—	—	80	A	
		IRFZ32	—	—	60	A	
V_{SD}	Diode Forward Voltage ②	IRFZ30	—	—	1.6	V	$T_C = 25^\circ\text{C}$, $I_S = 30\text{A}$, $V_{GS} = 0\text{V}$
		IRFZ32	—	—	1.5	V	$T_C = 25^\circ\text{C}$, $I_S = 25\text{A}$, $V_{GS} = 0\text{V}$
t_{rr}	Reverse Recovery Time	ALL	—	160	—	ns	$T_J = 150^\circ\text{C}$, $I_F = 30\text{A}$, $dI_F/dt = 100\text{A}/\mu\text{s}$
Q_{RR}	Reverse Recovered Charge	ALL	—	1.5	—	μC	$T_J = 150^\circ\text{C}$, $I_F = 30\text{A}$, $dI_F/dt = 100\text{A}/\mu\text{s}$
t_{on}	Forward Turn-on Time	ALL	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$.				

① $T_J = 25^\circ\text{C}$ to 150°C . ② Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

③ Repetitive Rating: Pulse width limited by max. junction temperature. See Transient Thermal Impedance Curve (Fig. 5).
④ $\text{K/W} = ^\circ\text{C/W}$
 $\text{W/K} = \text{W}/^\circ\text{C}$

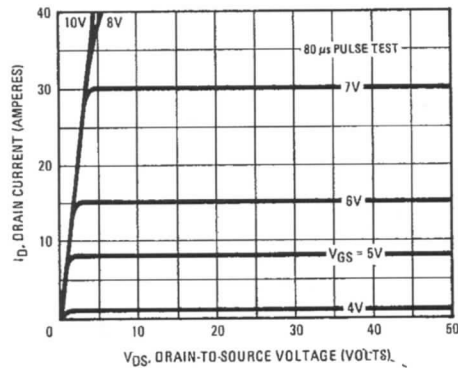


Fig. 1 — Typical Output Characteristics

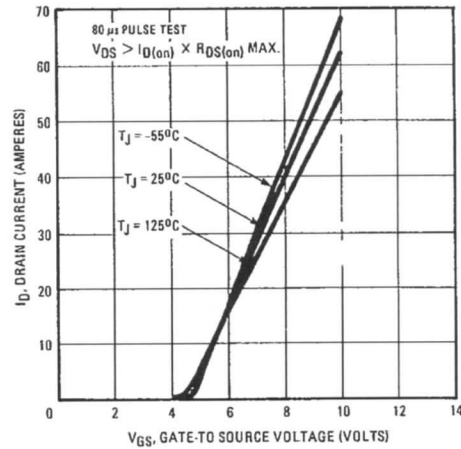


Fig. 2 — Typical Transfer Characteristics

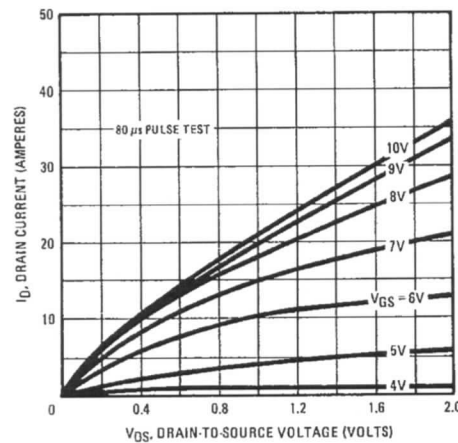


Fig. 3 — Typical Saturation Characteristics

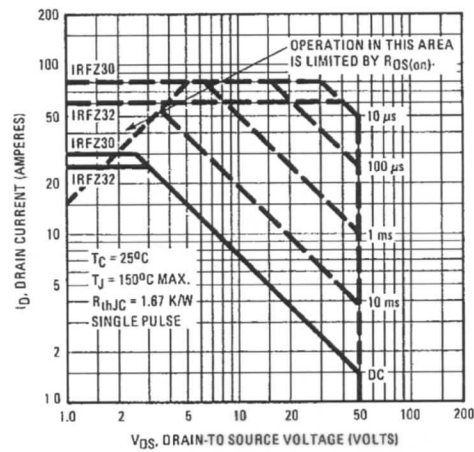


Fig. 4 — Maximum Safe Operating Area